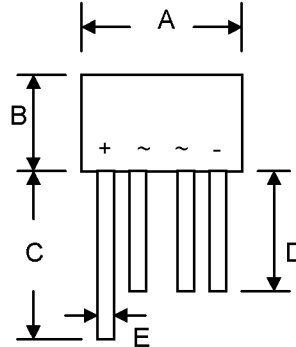


### Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

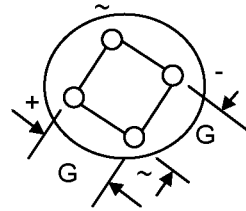


Dim	WOB	
	Min	Max
A	8.60	9.10
B	5.0	5.50
C	27.9	—
D	25.4	—
E	0.71	0.81
G	4.60	5.60

All Dimensions in mm

### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.1 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



### Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B40C 1000	B80C 1000	B125C 1000	B250C 1000	B380C 1000	B500C 1000	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$							V
Working Peak Reverse Voltage	$V_{RWM}$	100	200	300	600	900	1200	
DC Blocking Voltage	$V_R$							
Input Voltage Recommended	$V_{R(RMS)}$	40	80	125	250	380	500	V
Average Rectified Output Current (Note 1) @ $T_A = 50^{\circ}\text{C}$	$I_o$	1.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	45						A
Forward Voltage (per element) @ $I_F = 1.0\text{A}$	$V_{FM}$	1.0						V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	$I_{RM}$	10 500						$\mu\text{A}$
Operating Temperature Range	$T_j$	-55 to +125						$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150						$^{\circ}\text{C}$

Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.

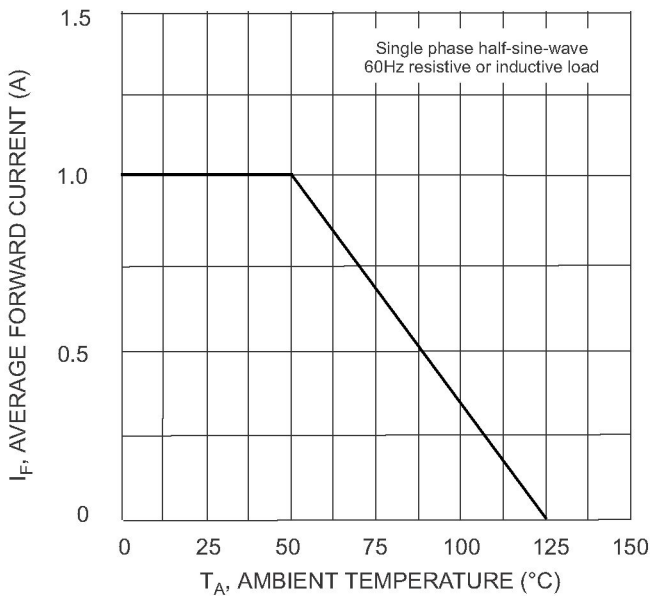


Fig. 1 Forward Current Derating Curve

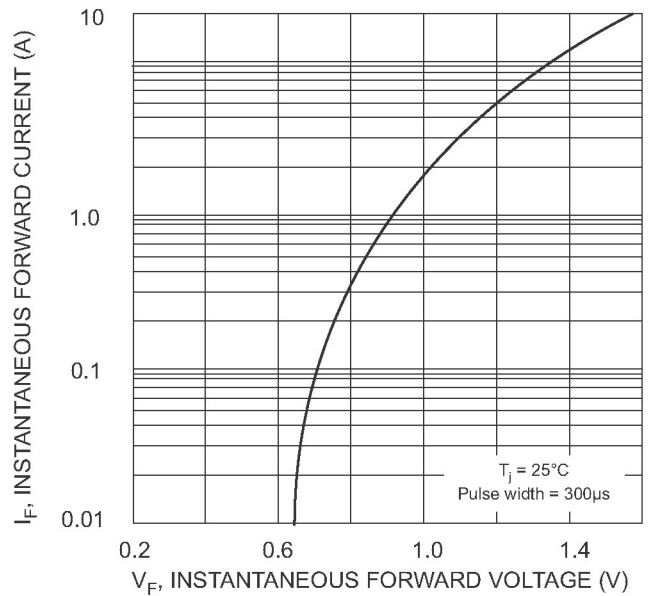


Fig. 2 Typical Forward Characteristics, per element

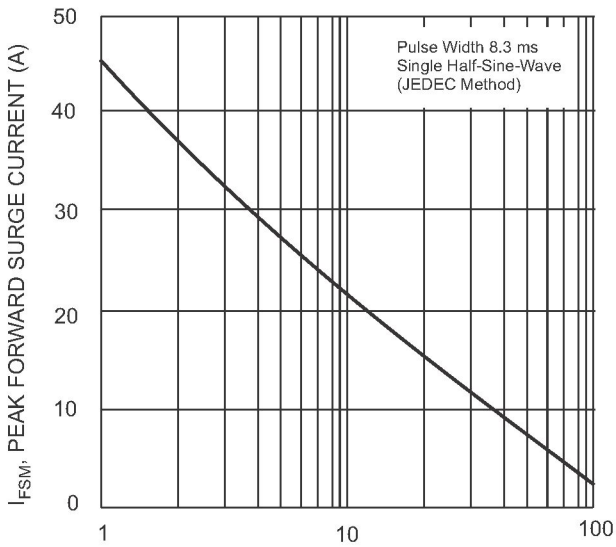


Fig. 3 Max Non-Repetitive Surge Current

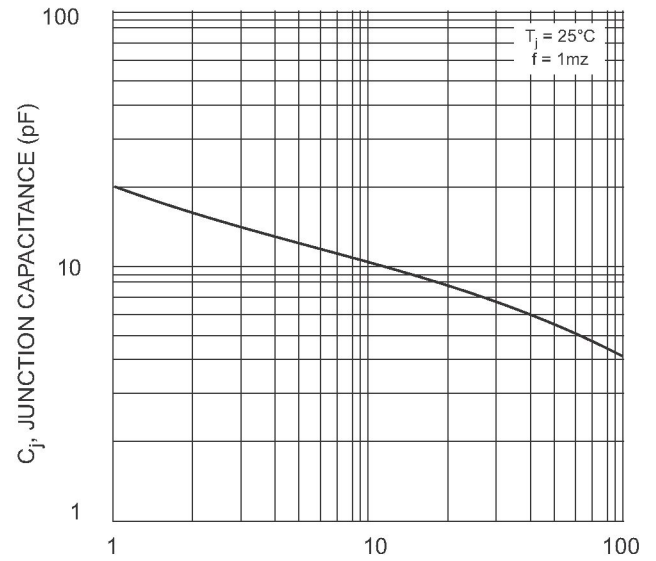


Fig. 4 Typical Junction Capacitance

